



## Simulation and Reliability Assessment of Advanced Packaging

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Deadline for manuscript  
submissions:

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### Message from the Guest Editor

Simulation-based technology plays an important role in the design, structure optimization, and evaluation of the reliability life of advanced packaging, which has become a design trend in the electronics packaging community. The purpose of this Special Issue is to introduce the latest research results of simulation-based technology in advanced packaging today, and the topics to be covered include material characterization of electronic packaging, theoretical or empirical work, modeling, simulation technology, design and validation, AI-assisted design-on-simulation technology, and reliability life prediction. Prospective authors are encouraged to contribute their original and unpublished works in the abovementioned areas.

It is my pleasure to invite you to submit a manuscript for this Special Issue. Full papers, letters, and reviews are all welcome.





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## Message from the Editor-in-Chief

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